

General Description

The MY5N10BF is Power MOSFET , Very low on-resistance ,which provides excellent $R_{DS(ON)}$ and efficiency for most of the small power switching and load switch applications.

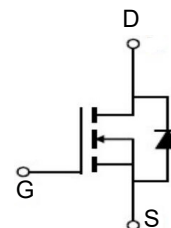
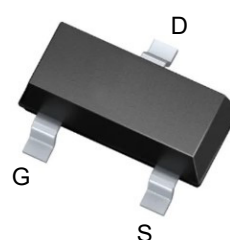


Features

V_{DSS}	100	V
I_D	5	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	110	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	125	$m\Omega$

Application

- Battery protection
- Load switch
- Power management



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY5N10BF	SOT-23	5N10	3000

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_{D@T_A=25^\circ C}$	Continuous Drain Current, V_{GS} @ 10V ¹	5	A
$I_{D@T_A=70^\circ C}$	Continuous Drain Current, V_{GS} @ 10V ¹	4.6	A
I_{DM}	Pulsed Drain Current ²	20	A
$P_{D@T_A=25^\circ C}$	Total Power Dissipation ³	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-ambient(steady state) ¹	135	$^\circ C/W$
	Thermal Resistance Junction-ambient($t < 10s$) ¹	85	$^\circ C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	---	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.122	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =2A	---	110	152	mΩ
		V _{GS} =4.5V, I _D =1A	---	125	158	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-4.84	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V, T _J =25°C	---	---	10	uA
		V _{DS} =80V, V _{GS} =0V, T _J =55°C	---	---	100	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =2A	---	10.2	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	2.3	4.6	Ω
Q _g	Total Gate Charge (10V)	V _{DS} =60V, V _{GS} =10V, I _D =2A	---	25.5	---	nC
Q _{gs}	Gate-Source Charge		---	4.2	---	
Q _{gd}	Gate-Drain Charge		---	4.3	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =50V, V _{GS} =10V, R _G =3.3 I _D =1A	---	17.3	---	ns
T _r	Rise Time		---	2.8	---	
T _{d(off)}	Turn-Off Delay Time		---	50	---	
T _f	Fall Time		---	2.8	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	1077	---	pF
C _{oss}	Output Capacitance		---	46	---	
C _{rss}	Reverse Transfer Capacitance		---	32	---	
I _S	Continuous Source Current ^{1,4}	V _G =V _D =0V, Force Current	---	---	2	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Electrical and Thermal Characteristics

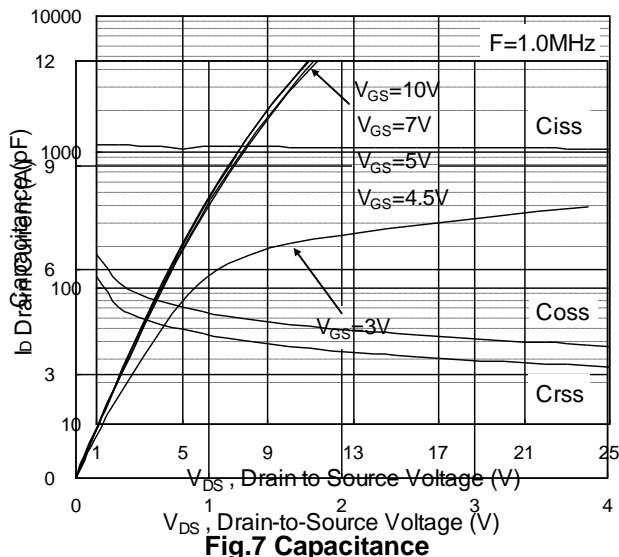


Fig.1 Typical Output Characteristics

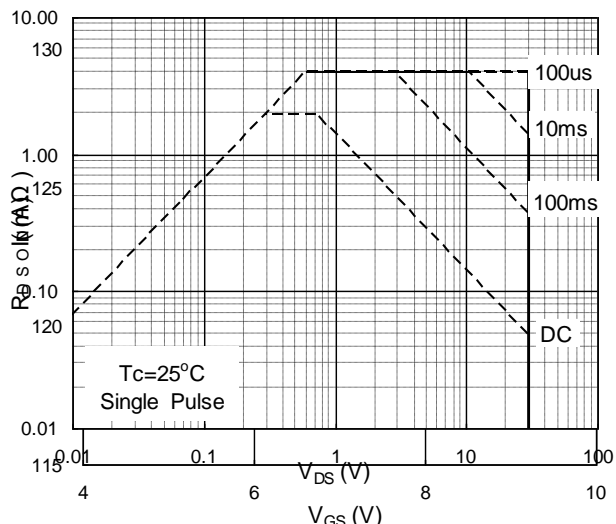


Fig.2 On-Resistance vs. Gate-Source

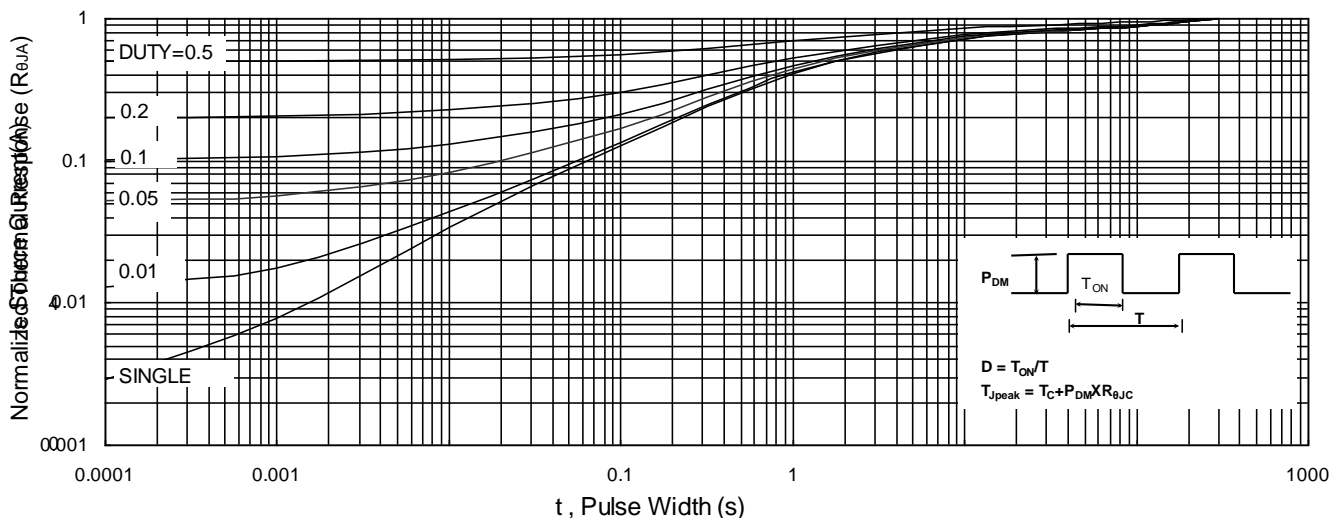


Fig.3 Forward Characteristics of Reverse

Fig.4 Gate-Charge Characteristics

Fig.9 Normalized Maximum Transient Thermal Impedance

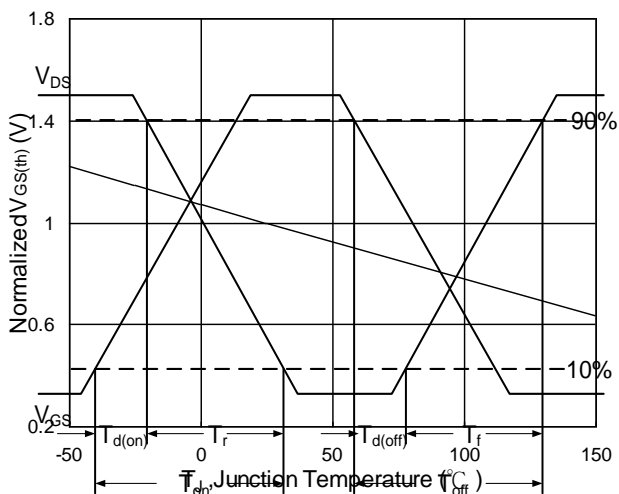


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

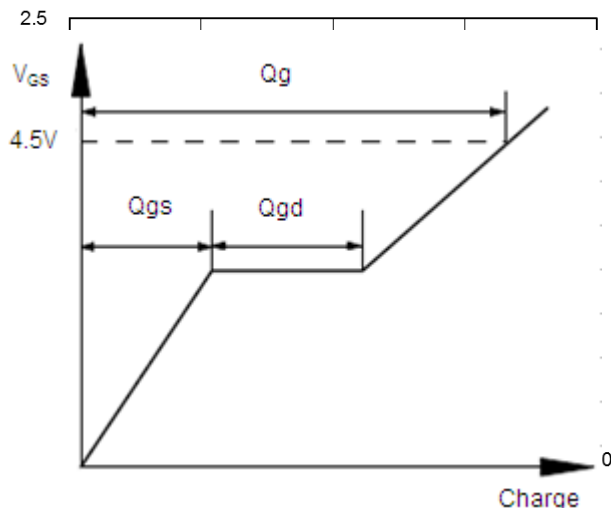


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

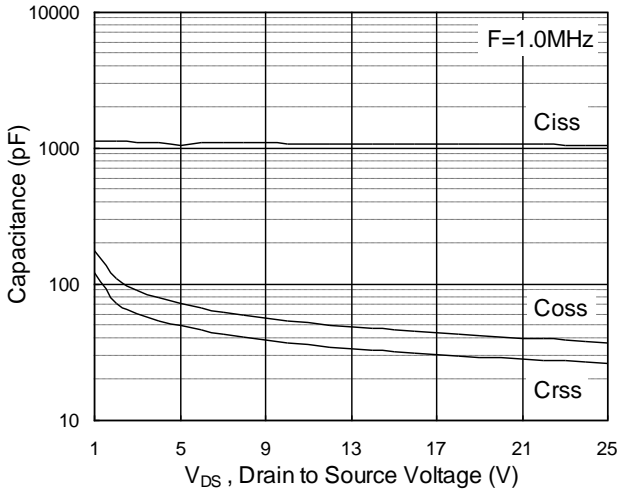


Fig.7 Capacitance

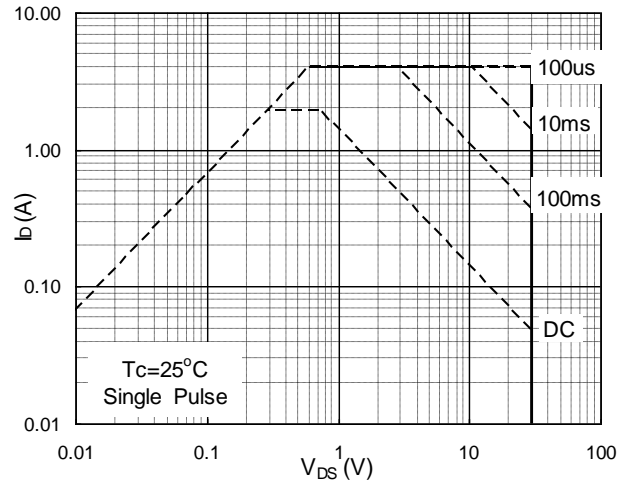


Fig.8 Safe Operating Area

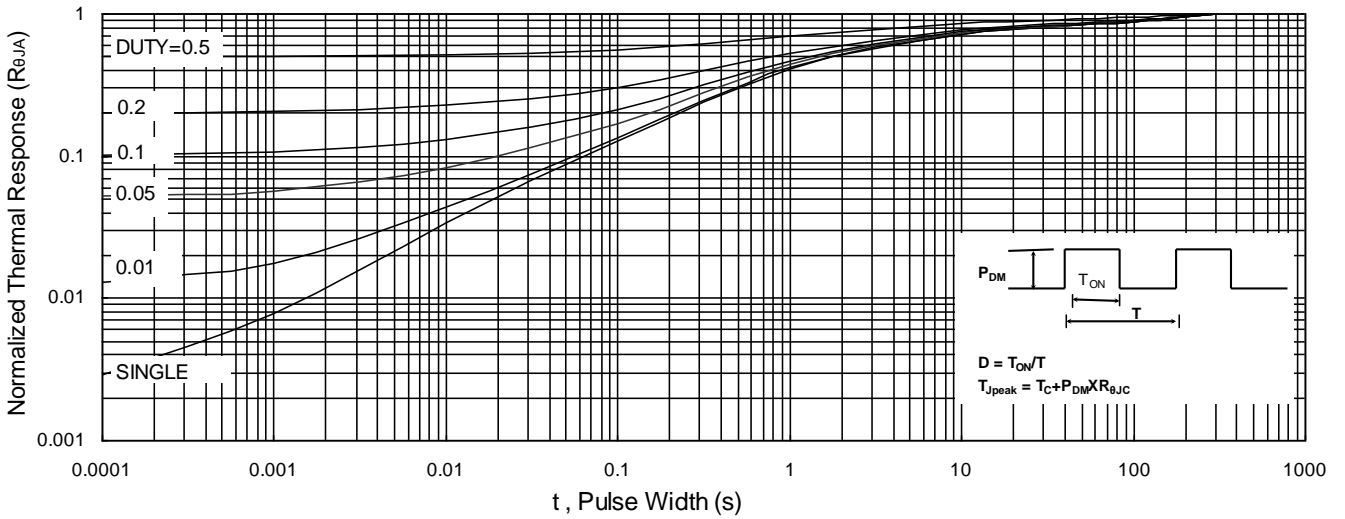


Fig.9 Normalized Maximum Transient Thermal Impedance

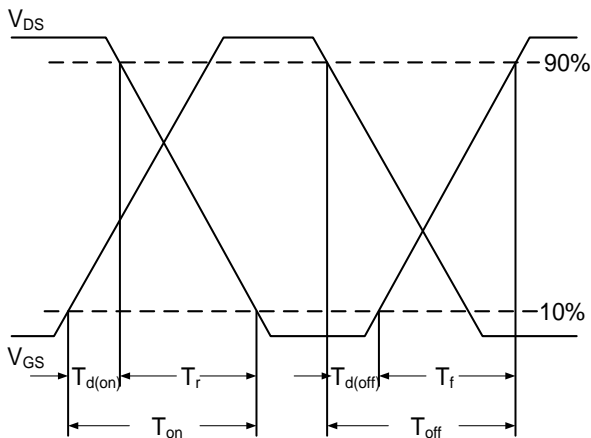


Fig.10 Switching Time Waveform

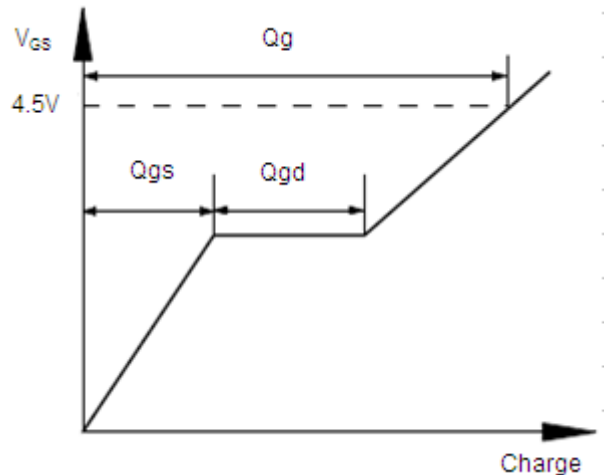
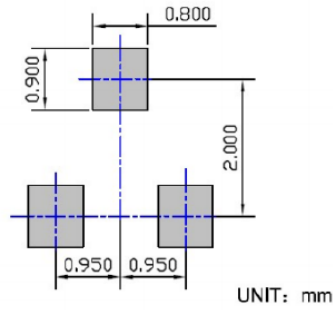
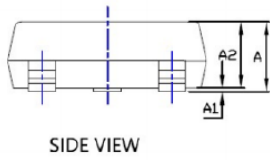
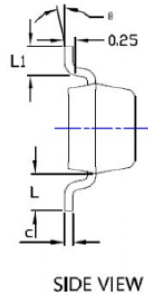
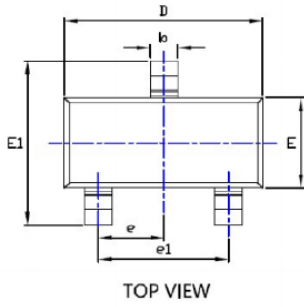


Fig.11 Gate Charge Waveform

Package Mechanical Data-SOT-23



SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	---	0.045	0.900	---	1.150
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.038	0.041	0.900	0.975	1.050
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.006	0.100	---	0.200
D	0.110	0.114	0.118	2.800	2.900	3.000
E	0.047	0.051	0.055	1.200	1.300	1.400
E1	0.089	0.094	0.100	2.250	2.400	2.550
e	0.037 TYP			0.950 TYP		
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.022 REF			0.550 REF		
L1	0.012	0.016	0.200	0.300	0.400	0.500
⊖	0°	---	8°	0°	---	8°

NOTE:
 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
 2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
 3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.